

PCN Number:	20190820005.1		PCN Date:	Aug 29 2019					
Title:	PBO to PI conversion for the OPA2211AIDRGR/T								
Customer Contact:	PCN Manager	Dept:	Quality Services						
Proposed 1st Ship Date:	Nov 29 2019	Estimated Sample Availability:	Date provided at sample request						
Change Type:									
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site				
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material				
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process				
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site				
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials				
				<input type="checkbox"/>	Wafer Fab Process				
PCN Details									
Description of Change:									
This notification is to announce the qualification of Polyimide as a replacement for the current PBO die coat for the OPA2211AIDRGR/T.									
<table border="1"> <thead> <tr> <th>Current</th> <th>Proposed</th> </tr> </thead> <tbody> <tr> <td>PBO</td> <td>PI</td> </tr> </tbody> </table>						Current	Proposed	PBO	PI
Current	Proposed								
PBO	PI								
Reason for Change:									
Continuity of Supply									
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):									
None									
Anticipated impact on Material Declaration									
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website .						
Changes to product identification resulting from this PCN:									
None									
Product Affected:									
OPA2211AIDRGR		OPA2211AIDRGT							

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: OPA2211AIDRG	QBS Product Reference: OPA2211IDDA	QBS Process Reference: OPA2140AIDGK	QBS Process Reference: OPA2209AIDGK	QBS Package Reference: SN0903049DRG
AC	Autoclave 121C	96 Hours	-	1/77/0	1/77/0	1/77/0	-
CDM	ESD - CDM	1000 V	1/3/0	1/3/0	1/3/0	1/3/0	-
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	Pass	-
HAST	Biased HAST 130C/85%RH	96 Hours	-	-	-	1/77/0	3/231/0
HBM	ESD - HBM	2500 V	-	-	-	1/3/0	-
HBM	ESD - HBM	3000 V	-	1/3/0	1/3/0	-	-
HTOL	Life Test, 125C	1000 Hours	-	-	1/77/0	1/77/0	-
HTOL	Life Test, 150C	300 Hours	-	-	-	-	1/77/0
HTSL	High Temp Storage Bake 170C	420 Hours	3/231/0	1/77/0	1/69/0	1/77/0	1/77/0
LU	Latch-up	(per JESD78)	-	1/6/0	1/6/0	1/6/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	1/77/0	1/77/0	1/77/0	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	3/231/0	-	-	-	2/154/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
 - The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
 - The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
 - The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

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